

Features

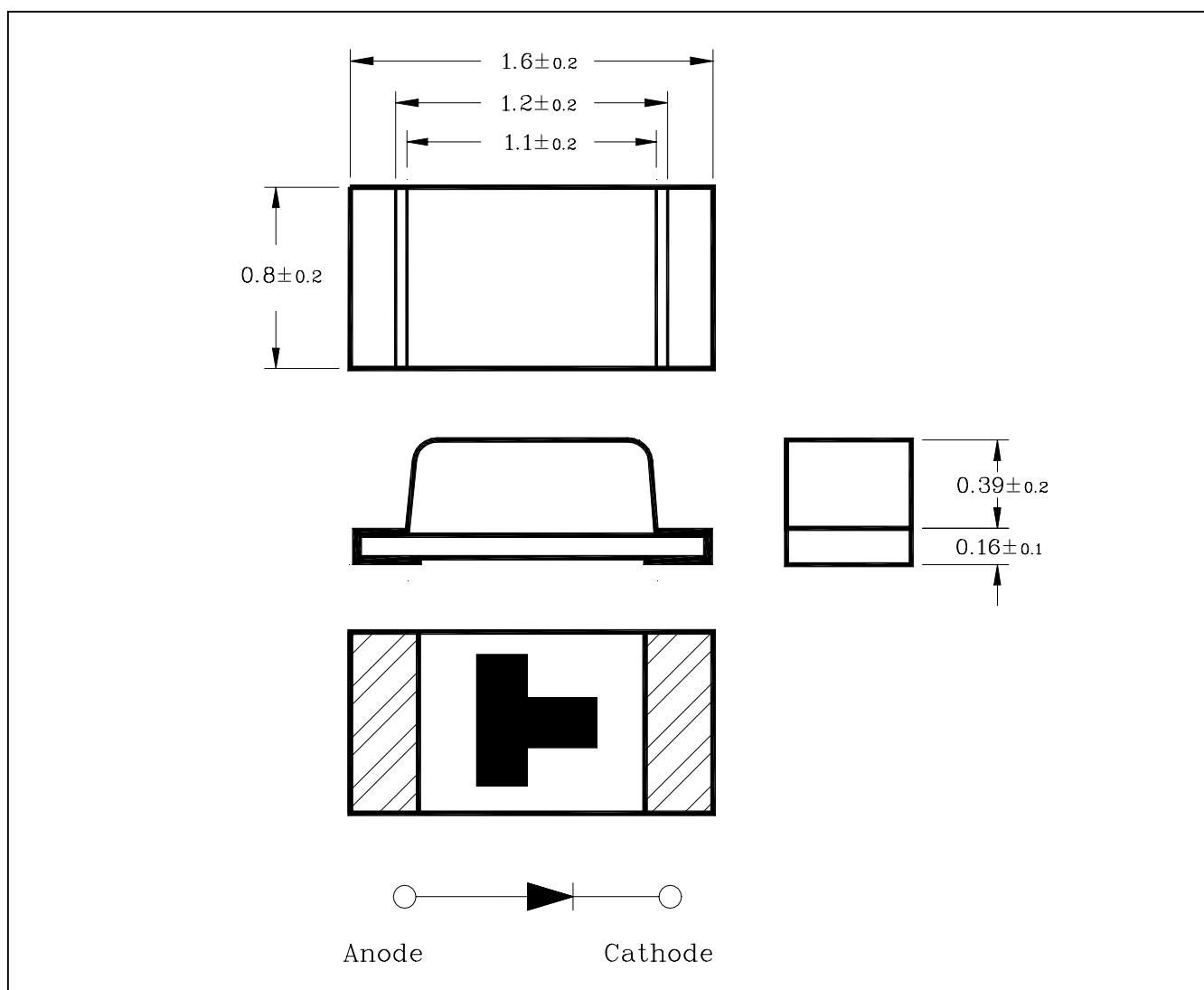
- 1.6mm(L)×0.8mm small size surface mount type
- Thin package of 0.55mm(H) thickness
- Transparent clear lens optic
- Low power consumption type chip LED

Applications

- LCD backlighting
- Keypad backlighting
- Symbol backlighting
- Front panel indicator lamp

Outline Dimensions

unit : mm



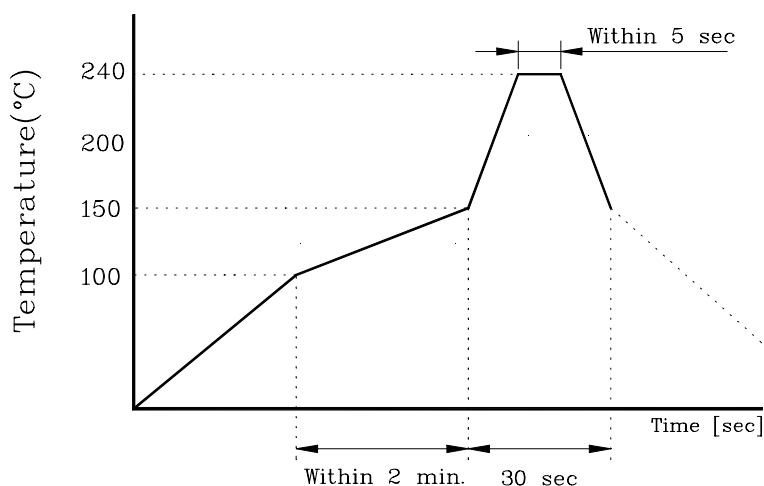
Absolute maximum ratings

| Characteristic | Symbol | Ratings | Unit |
|-------------------------|-----------|-------------------|------|
| Power Dissipation | P_D | 70 | mW |
| Forward Current | I_F | 25 | mA |
| *1Peak Forward Current | I_{FP} | 50 | mA |
| Reverse Voltage | V_R | 4 | V |
| Operating Temperature | T_{opr} | -25 80 | |
| Storage Temperature | T_{stg} | -30 100 | |
| *2Soldering Temperature | T_{sol} | 240 for 5 seconds | |

*1. Duty ratio = 1/16, Pulse width = 0.1ms

*2. Recommended soldering Temperature Profile

- 2-1) Preheating 100 to 150 within 2 minutes Soldering 240 within 5 seconds
- Gradual cooling (Avoid quenching)



Electrical Characteristics

| Characteristic | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|--------------------|----------------|----------------|------|----------|------|---------|
| Forward Voltage | V_F | $I_F = 20mA$ | - | 2.0 | 2.8 | V |
| Luminous Intensity | I_V | $I_F = 20mA$ | - | 4 | - | mcd |
| Peak Wavelength | λ_p | $I_F = 20mA$ | - | 615 | - | nm |
| Spectrum Bandwidth | | $I_F = 20mA$ | - | 35 | - | nm |
| Reverse Current | I_R | $V_R = 4V$ | - | - | 10 | μA |
| *3Half Angle | $\theta_{1/2}$ | $I_F = 20mA$ | - | ± 65 | - | deg |
| | Y | | - | ± 70 | - | |

Characteristic Diagrams

Fig. 1 $I_F - V_F$

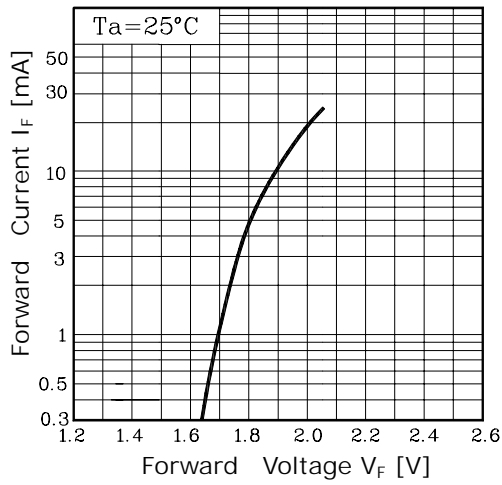


Fig. 2 $I_V - I_F$

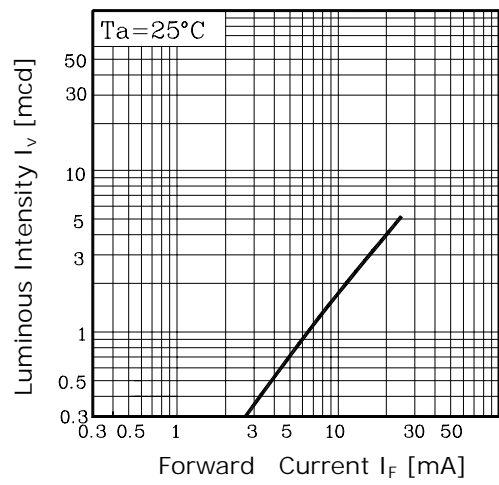


Fig. 3 $I_F - T_a$

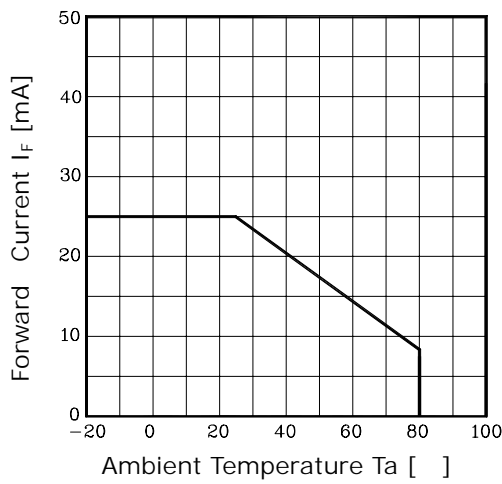


Fig. 4 Spectrum Distribution

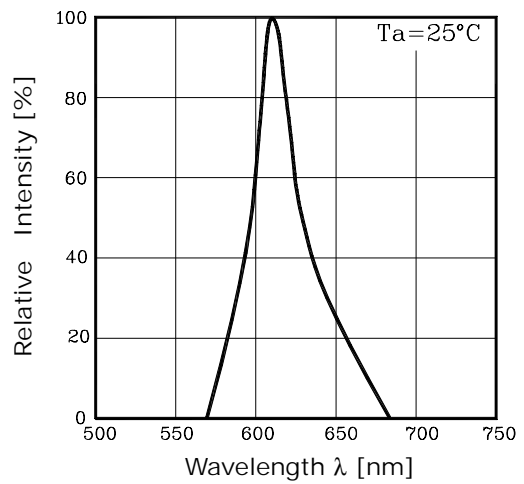


Fig. 5-1 Radiation Diagram(X)

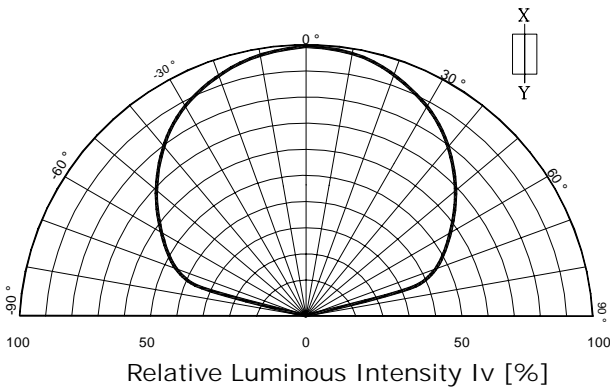


Fig. 5-2 Radiation Diagram(Y)

